# E·XFL

### Intel - 5CGTFD7C5F23I7N Datasheet



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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	56480
Number of Logic Elements/Cells	149500
Total RAM Bits	7880704
Number of I/O	240
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgtfd7c5f23i7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# **Cyclone V Device Overview**

The Cyclone<sup>®</sup> V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

#### **Related Information**

Cyclone V Device Handbook: Known Issues Lists the planned updates to the Cyclone V Device Handbook chapters.

# **Key Advantages of Cyclone V Devices**

#### Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	<ul> <li>Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks</li> <li>Up to 40% lower power consumption than the previous generation device</li> </ul>
Improved logic integration and differentiation capabilities	<ul> <li>8-input adaptive logic module (ALM)</li> <li>Up to 13.59 megabits (Mb) of embedded memory</li> <li>Variable-precision digital signal processing (DSP) blocks</li> </ul>
Increased bandwidth capacity	<ul><li>3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers</li><li>Hard memory controllers</li></ul>
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul> <li>Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Lowest system cost	<ul> <li>Requires only two core voltages to operate</li> <li>Available in low-cost wirebond packaging</li> <li>Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration</li> </ul>

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# **Summary of Cyclone V Features**

# Table 2. Summary of Features for Cyclone V Devices

Feature		Description						
Technology	<ul><li>TSMC's 28-nm low-p</li><li>1.1 V core voltage</li></ul>	······································						
Packaging	<ul> <li>Multiple device densi different device dens</li> </ul>	Wirebond low-halogen packages Multiple device densities with compatible package footprints for seamless migration between different device densities RoHS-compliant and leaded <sup>(1)</sup> options						
High-performance FPGA fabric	Enhanced 8-input ALM w	inhanced 8-input ALM with four registers						
Internal memory blocks		b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory						
Embedded Hard IP blocks	Variable-precision DSP	<ul> <li>Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block</li> <li>64-bit accumulator and cascade</li> <li>Embedded internal coefficient memory</li> <li>Preadder/subtractor for improved efficiency</li> </ul>						
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support						
	Embedded transceiver I/OPCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port							
Clock networks	, , , ,	l clock network d peripheral clock networks are not used can be powered down to reduce dynamic power						
Phase-locked loops (PLLs)	<ul><li> Precision clock synth</li><li> Integer mode and fra</li></ul>	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode						
FPGA General-purpose I/Os (GPIOs)	<ul><li>400 MHz/800 Mbps e</li><li>On-chip termination</li></ul>	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength						
Low-power high-speed serial interface	Transmit pre-emphase	ibps integrated transceiver speed sis and receiver equalization nfiguration of individual channels						
HPS (Cyclone V SE, SX, and ST devices only)	<ul> <li>Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing</li> <li>Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I<sup>2</sup>C interface, and up to 85 HPS GPIO interfaces</li> </ul>							
	<ul> <li>System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers</li> <li>On-chip RAM and boot ROM</li> </ul>							
		continued						

<sup>&</sup>lt;sup>(1)</sup> Contact Intel for availability.



Feature	Description
	<ul> <li>HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa</li> <li>FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller</li> <li>Arm CoreSight<sup>™</sup> JTAG debug access port, trace port, and on-chip trace storage</li> </ul>
Configuration	<ul> <li>Tamper protection—comprehensive design protection to protect your valuable IP investments</li> <li>Enhanced advanced encryption standard (AES) design security features</li> <li>CvP</li> <li>Dynamic reconfiguration of the FPGA</li> <li>Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options</li> <li>Internal scrubbing <sup>(2)</sup></li> <li>Partial reconfiguration <sup>(3)</sup></li> </ul>

# **Cyclone V Device Variants and Packages**

### Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

### Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

#### **Related Information**

#### Product Selector Guide

Provides the latest information about Intel products.

<sup>(2)</sup> The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

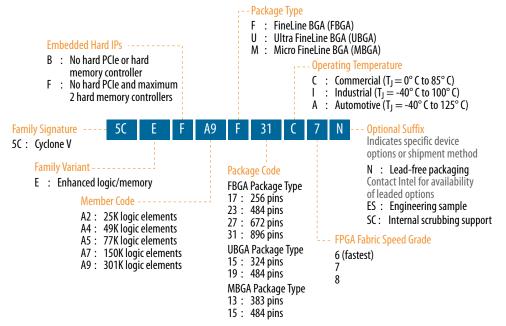
<sup>(3)</sup> The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel<sup>®</sup> sales representatives.



### **Available Options**

### Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



### **Maximum Resources**

#### Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource				Member Code		
		A2	A4	A5	A7	A9
Logic Elements	(LE) (K)	25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precisi	on DSP Block	25	66	150	156	342
18 x 18 Multipli	er	50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory C	ontroller	1	1	2	2	2



### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

### **Package Plan**

#### Table 5. Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO							
A2	223	-	176	128	224	224	-	_
A4	223	-	176	128	224	224	-	_
A5	175	-	_	_	224	240	-	_
A7	-	240	_	_	240	240	336	480
A9	-	-	-	_	240	224	336	480

# **Cyclone V GX**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

### **Related Information**

Product Selector Guide

Provides the latest information about Intel products.



Resource		Member Code							
		C3	C4	C5	C7	С9			
LVDS	Transmitter	52	84	84	120	140			
	Receiver	52	84	84	120	140			
PCIe Hard IP Block		1	2	2	2	2			
Hard Memory Controller		1	2	2	2	2			

### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

### Package Plan

### Table 7. Package Plan for Cyclone V GX Devices

Member Code	r M301 (11 mm)					U324 (15 mm)		U484 (19 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	_	_	_	_	_	_	144	3	208	3
C4	129	4	175	6	_	_	_	-	224	6
C5	129	4	175	6	_	_	_	_	224	6
C7	—	—	—	—	240	3	—		240	6
C9	_	_	_	_	_	_	_		240	5

Member Code	F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	_	_	_	_	_	-
C4	240	6	336	6	_	_	_	-
C5	240	6	336	6	_	_	_	-
C7	240	6	336	9	480	9	_	-
C9	224	6	336	9	480	12	560	12

# **Cyclone V GT**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

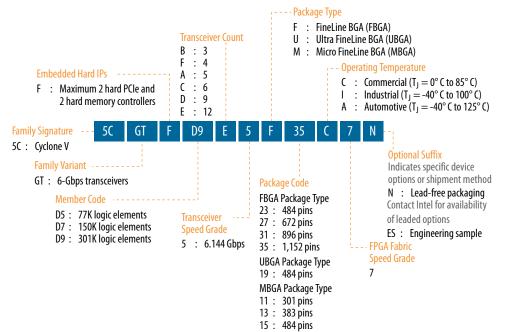
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### **Available Options**

### Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



### **Maximum Resources**

#### Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code					
		D5	D7	D9				
Logic Elements (LE) (	К)	77	150	301				
ALM		29,080	56,480	113,560				
Register		116,320	225,920	454,240				
Memory (Kb)	M10K	4,460	6,860	12,200				
	MLAB	424	836	1,717				
Variable-precision DS	P Block	150	156	342				
18 x 18 Multiplier		300	312	684				
PLL		6	7	8				
6 Gbps Transceiver		6	9	12				
GPIO <sup>(5)</sup>		336	480	560				
LVDS	Transmitter	84	84 120					
				continued				

<sup>&</sup>lt;sup>(5)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



# **Cyclone V SE**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

#### Product Selector Guide

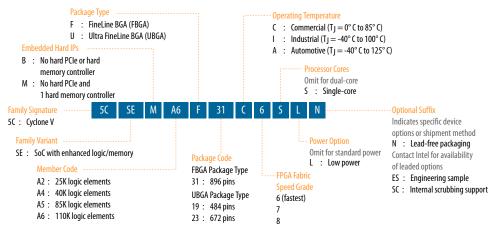
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### **Available Options**

#### Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

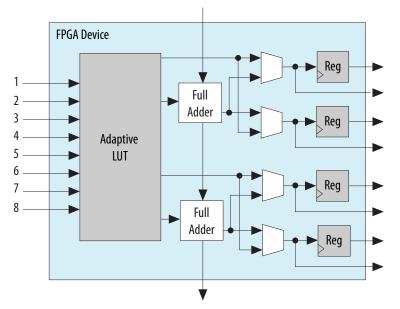
The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





#### Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

#### **Related Information**

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

# **Variable-Precision DSP Block**

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



Variant	Member Code	Variable- precision DSP Block	-	dent Input and plications Ope	18 x 18 Multiplier Adder Mode	18 x 18 Multiplier		
		DSP BIOCK	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input	
	C6	112	336	224	112	112	112	
Cyclone V ST	D5	87	261	174	87	87	87	
	D6	112	336	224	112	112	112	

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

# **Types of Embedded Memory**

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

# **Embedded Memory Capacity in Cyclone V Devices**

### Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Member	M1	.0К	ML	MLAB	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



	Member	M1	M10K		MLAB	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

# **Embedded Memory Configurations**

### Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1К	x10 or x8
	2К	x5 or x4
	4К	x2
	8К	×1

# **Clock Networks and PLL Clock Sources**

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

*Note:* To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



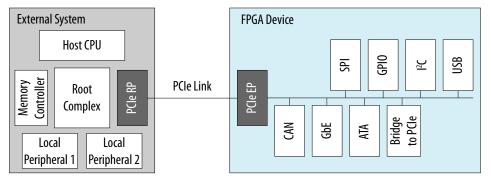
# PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

### Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

# **External Memory Interface**

This section provides an overview of the external memory interface in Cyclone V devices.

### Hard and Soft Memory Controllers

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



# **External Memory Performance**

### Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Frequency (MHz)		Minimum Frequency
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

#### **Related Information**

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

### **HPS External Memory Performance**

### Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

### **Related Information**

#### External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

# **Low-Power Serial Transceivers**

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

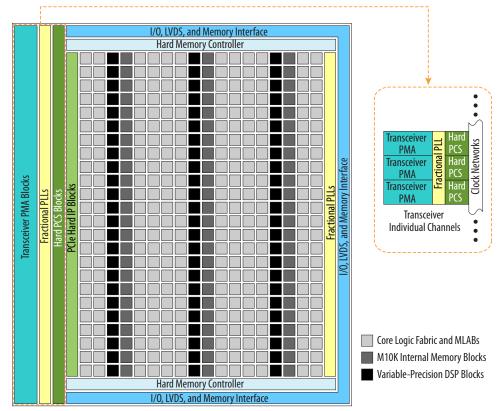
### **Transceiver Channels**

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



### Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



### **PMA Features**

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

#### Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	<ul> <li>Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization</li> <li>No decision feedback equalizer (DFE)</li> </ul>
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels



# **PCS Features**

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO<sup>®</sup> (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23.	<b>Transceiver PCS</b>	Features for C	vclone V Devices
		i cutui co i ci c	

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	<ul> <li>Phase compensation FIFO</li> <li>Byte serializer</li> <li>8B/10B encoder</li> <li>Transmitter bit-slip</li> </ul>	<ul> <li>Word aligner</li> <li>Deskew FIFO</li> <li>Rate-match FIFO</li> <li>8B/10B decoder</li> <li>Byte deserializer</li> <li>Byte ordering</li> <li>Receiver phase compensation FIFO</li> </ul>
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	<ul> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core</li> </ul>	<ul> <li>Dedicated PCIe PHY IP core</li> <li>PIPE 2.0 interface to the core logic</li> </ul>
PCIe Gen2 ( x1, x2, x4) <sup>(12)</sup>		logic	logic
GbE	1.25	<ul> <li>Custom PHY IP core with preset feature</li> <li>GbE transmitter synchronization state machine</li> </ul>	<ul> <li>Custom PHY IP core with preset feature</li> <li>GbE receiver synchronization state machine</li> </ul>
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	<ul> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 channel bonding</li> </ul>	<ul> <li>Custom PHY IP core with preset feature</li> <li>SRIO version 2.1-compliant x2 and x4 deskew state machine</li> </ul>
SDI, SD/HD, and 3G-SDI	0.27 <sup>(14)</sup> , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 <sup>(15)</sup> to 3.125		
	•	•	continued

<sup>&</sup>lt;sup>(12)</sup> PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

- <sup>(13)</sup> XAUI is supported through the soft PCS.
- $^{(14)}$  The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
- <sup>(15)</sup> The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



### **HPS-FPGA AXI Bridges**

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA<sup>®</sup>) Advanced eXtensible Interface (AXI<sup>™</sup>) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

### **HPS SDRAM Controller Subsystem**

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon<sup>®</sup> Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

### **FPGA Configuration and Processor Booting**

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
  partially reconfigure the FPGA fabric at any time under software control. The HPS
  can also configure other FPGAs on the board through the FPGA configuration
  controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.



*Note:* Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

### **Related Information**

Cyclone V Device Family Pin Connection Guidelines

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

### **Hardware and Software Development**

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks<sup>®</sup>, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

#### **Related Information**

International Altera Sales Support Offices

# **Dynamic and Partial Reconfiguration**

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

### **Dynamic Reconfiguration**

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

### **Partial Reconfiguration**

*Note:* The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



# **Power Management**

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

# **Document Revision History for Cyclone V Device Overview**

Document Version	Changes
2018.05.07	<ul> <li>Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams.</li> <li>Rebranded as Intel.</li> </ul>

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to $-7$ in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	<ul> <li>Added descriptions to package plan tables for Cyclone V GT and ST devices.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.12	<ul> <li>Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives.</li> <li>Updated logic elements (LE) (K) for the following devices: <ul> <li>Cyclone V E A7: Updated from 149.5 to 150</li> <li>Cyclone V GX C3: Updated from 149.7 to 150</li> <li>Cyclone V GT D7: Updated from 149.5 to 150</li> <li>Cyclone V GT D7: Updated from 149.5 to 150</li> </ul> </li> <li>Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: <ul> <li>Cyclone V GX C3: Updated from 291 to 182</li> <li>Cyclone V GX C4: Updated from 678 to 424</li> <li>Cyclone V GX C7: Updated from 1,338 to 836</li> <li>Cyclone V GX C9: Updated from 1,717</li> </ul> </li> </ul>
	1	continued

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•Updated MLAB RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V GX G3: Updated from 181 to 182 - Cyclone V GX G4: Updated from 25 to 243 • Updated Total RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: - Cyclone V GX G3: Updated from 1,531 to 1,532 - Cyclone V GX G4: Updated from 2,795 to 2,924March 20152015.03.31• Added Internal Scrubbing Fedure under configuration in Summary of Fedures for Cyclone V Devices table as follows: - Cyclone V GX G4: Updated from 7,975 to 2,924 - Cyclone V GX G4: Updated from 7,975 to 2,924March 20152015.03.31• Added Internal Scrubbing Fedure under configuration in Summary of Fedures for Cyclone V Devices table. - Added optional suffix "SC: Internal scrubbing support" to the following diagrams: - Sample Ordering Code and Available Options for Cyclone V SE Devices - Sample Ordering Code and Available Options for Cyclone V SE Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices four because Cyclone V ST devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices four because Cyclone V ST devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Operating Temperature: Removed C and A temperature grades - Updated the transceiver specification for Cyclone V ST Devices - Device Variants for the Cyclone V Device Family table - Sample Ordering Code and Available Options for Cyclone V ST Devices - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V ST Devices - Device Variants for the Cyclone V Devic	Date	Version	Changes
Features for Cyclone V Devices table.• Added optional suffix "SC: Internal scrubbing support" to the following diagrams:- Sample Ordering Code and Available Options for Cyclone V E Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V STDevices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade Operating Temperature: Removed C and A temperature grades- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver counts for Cyclone V ST Devices- Updated Maximum Resource Counts for Cyclone V ST Devices- Logic elements (LE) (K): Updated from 51 to 57- 18 × 18 multiplier: Updated from 51 to 57- 9 × 9 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit Input: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit 17- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier:			<ul> <li>Distribution in Cyclone V Devices table as follows:</li> <li>Cyclone V GX C3: Updated from 181 to 182</li> <li>Cyclone V GX C4: Updated from 295 to 424</li> <li>Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:</li> <li>Cyclone V GX C3: Updated from 1,531 to 1,532</li> <li>Cyclone V GX C4: Updated from 2,795 to 2,924</li> <li>Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:</li> <li>Cyclone V GX C4: Updated from 2,795 to 2,924</li> <li>Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:</li> <li>Cyclone V GX C4: Updated from 472 to 678</li> </ul>
Devices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade. 	March 2015	2015.03.31	<ul> <li>Features for Cyclone V Devices table.</li> <li>Added optional suffix "SC: Internal scrubbing support" to the following diagrams: <ul> <li>Sample Ordering Code and Available Options for Cyclone V E Devices</li> <li>Sample Ordering Code and Available Options for Cyclone V GX Devices</li> <li>Sample Ordering Code and Available Options for Cyclone V SE Devices</li> </ul> </li> </ul>
	January 2015	2015.01.23	<ul> <li>Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade.</li> <li>Operating Temperature: Removed C and A temperature grades</li> <li>FPGA Fabric Speed Grade: Removed -6 and -8 speed grades</li> <li>Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: <ul> <li>Device Variants for the Cyclone V Device Family table</li> <li>Sample Ordering Code and Available Options for Cyclone V ST Devices figure</li> <li>Maximum Resource Counts for Cyclone V ST Devices</li> </ul> </li> <li>Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. <ul> <li>Logic elements (LE) (K): Updated from 35.7 to 35.5</li> <li>Variable-precision DSP block: Updated from 51 to 57</li> <li>18 × 18 multiplier: Updated from 102 to 114</li> </ul> </li> <li>Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. <ul> <li>Variableprecision DSP Block: Updated from 51 to 57</li> <li>9 × 9 Multiplier: Updated from 153 to 171</li> <li>18 × 18 Multiplier: Updated from 102 to 114</li> <li>27 × 27 Multiplier: Updated from 51 to 57</li> <li>18 × 18 Multiplier Adder Mode: Updated from 51 to 57</li> <li>18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57</li> <li>18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57</li> <li>M10K RAM bit (Kb): Updated from 1,190 to 1,350</li> <li>MLAB block: Updated from 255 to 291</li> <li>MLAB RAM bit (Kb): Updated from 159 to 181</li> </ul> </li> </ul>
	October 2014	2014.10.06	

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Date	Version	Changes
		<ul> <li>Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.</li> <li>Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.</li> <li>Text edits throughout the document.</li> </ul>
February 2012	1.2	<ul> <li>Updated Table 1–2, Table 1–3, and Table 1–6.</li> <li>Updated "Cyclone V Family Plan" on page 1–4 and "Clock Networks and PLL Clock Sources" on page 1–15.</li> <li>Updated Figure 1–1 and Figure 1–6.</li> </ul>
November 2011	1.1	<ul> <li>Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–5, and Table 1–6.</li> <li>Updated Figure 1–4, Figure 1–5, Figure 1–6, Figure 1–7, and Figure 1–8.</li> <li>Updated "System Peripherals" on page 1–18, "HPS–FPGA AXI Bridges" on page 1–19, "HPS SDRAM Controller Subsystem" on page 1–19, "FPGA Configuration and Processor Booting" on page 1–19, and "Hardware and Software Development" on page 1–20.</li> <li>Minor text edits.</li> </ul>
October 2011	1.0	Initial release.